

## 阅读申明

- 1.本站收集的数据手册和产品资料都来自互联网，版权归原作者所有。如读者和版权方有任何异议请及时告之，我们将妥善解决。
- 2.本站提供的中文数据手册是英文数据手册的中文翻译，其目的是协助用户阅读，该译文无法自动跟随原稿更新，同时也可能存在翻译上的不当。建议读者以英文原稿为参考以便获得更精准的信息。
- 3.本站提供的产品资料，来自厂商的技术支持或者使用者的心得体会等，其内容可能存在描述上的差异，建议读者做出适当判断。
- 4.如需与我们联系，请发邮件到marketing@iczoom.com，主题请标有“数据手册”字样。

## Read Statement

1. The datasheets and other product information on the site are all from network reference or other public materials, and the copyright belongs to the original author and original published source. If readers and copyright owners have any objections, please contact us and we will deal with it in a timely manner.
2. The Chinese datasheets provided on the website is a Chinese translation of the English datasheets. Its purpose is for reader's learning exchange only and do not involve commercial purposes. The translation cannot be automatically updated with the original manuscript, and there may also be improper translations. Readers are advised to use the English manuscript as a reference for more accurate information.
3. All product information provided on the website refer to solutions from manufacturers' technical support or users the contents may have differences in description, and readers are advised to take the original article as the standard.
4. If you have any questions, please contact us at marketing@iczoom.com and mark the subject with "Datasheets" .

# AS1744, AS1745

## High-Speed, Low-Voltage, Dual, Single-Supply, 4Ω, SPDT Analog Switches

Data Sheet

### 1 General Description

The AS1744/AS1745 are high-speed, low-voltage, dual single-pole/double-throw (SPDT) analog switches.

Fast switching speeds, low ON-resistance, and low power-consumption make these devices ideal for single-cell battery powered applications.

These highly-reliable devices operate from a +1.8 to +5.5V supply, are differentiated by inverted logic, and support break-before-make switching.

With low ON-resistance ( $R_{ON}$ ),  $R_{ON}$  matching, and  $R_{ON}$  flatness, the devices can accurately switch signals for sample and hold circuits, digital filters, and op-amp gain switching networks.

The devices are available in a 10-pin MSOP package and a 10-pin TDFN package.

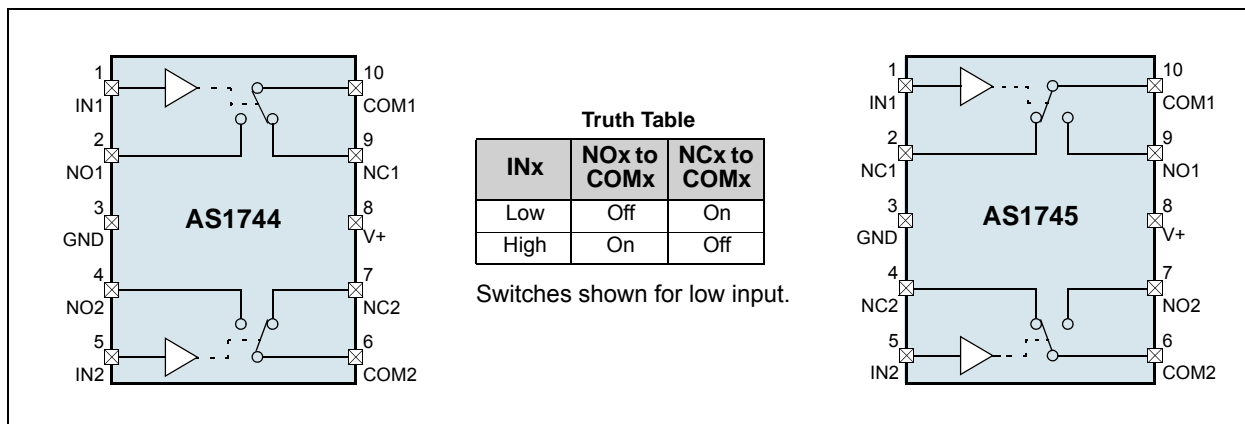
### 2 Key Features

- ON-Resistance:
  - 4Ω (+5V supply)
  - 5.5Ω (+3V supply)
- $R_{ON}$  Matching: 0.2Ω (+5V supply)
- $R_{ON}$  Flatness: 1Ω (+5V supply)
- Supply Voltage Range: +1.8 to +5.5V
- 1.8V Operation:
  - 9.5Ω ON-Resistance over Temperature
  - 38ns Turn On Time
  - 12ns Turn Off Time
- Current-Handling: 100mA Continuous
- Break-Before-Make Switching
- Rail-to-Rail Signal Handling
- Crosstalk: -90dB at 1MHz
- Off-Isolation: -85dB at 1MHz
- Total Harmonic Distortion: 0.1%
- Operating Temperature Range: -40 to +85°C
- Package Types:
  - 10-pin MSOP
  - 10-pin TDFN

### 3 Applications

The devices are ideal for use in power routing systems, cordless and mobile phones, MP3 players, CD and DVD players, PDAs, handheld computers, digital cameras, and any other application where high-speed signal switching is required.

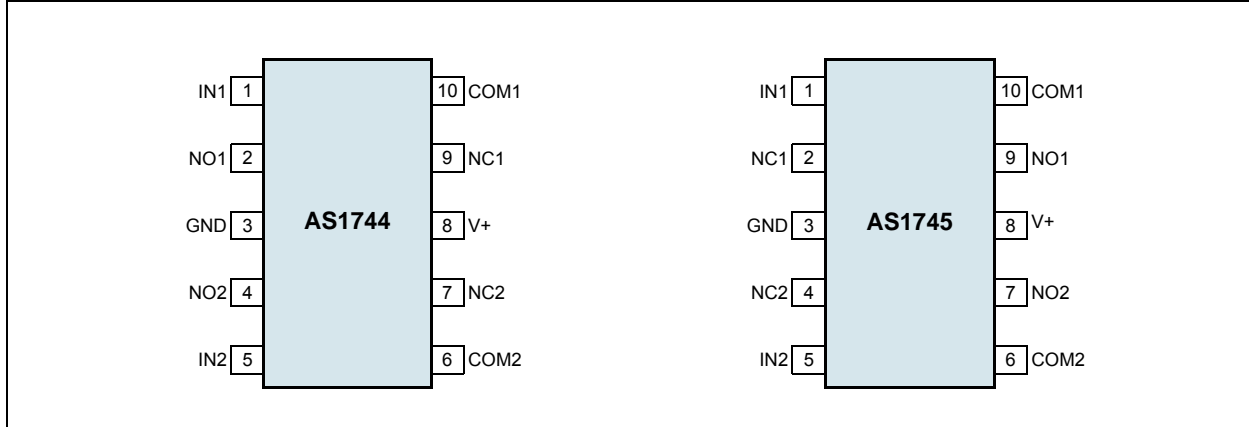
Figure 1. Block Diagrams



## 4 Pinout

### Pin Assignments

Figure 2. Pin Assignments (Top View)



### Pin Descriptions

Table 1. Pin Descriptions

Pin Number		Pin Name	Description
AS1744	AS1745		
10	10	COM1	<b>Analog Switch 1 Common</b>
6	6	COM2	<b>Analog Switch 2 Common</b>
3	3	GND	<b>Ground</b>
1	1	IN1	<b>Analog Switch 1 Logic Control Input</b>
5	5	IN2	<b>Analog Switch 2 Logic Control Input</b>
9	2	NC1	<b>Analog Switch 1 Normally Closed Terminal</b>
7	4	NC2	<b>Analog Switch 2 Normally Closed Terminal</b>
2	9	NO1	<b>Analog Switch 1 Normally Open Terminal</b>
4	7	NO2	<b>Analog Switch 2 Normally Open Terminal</b>
8	8	V+	<b>Input Supply Voltage. +1.8 to +5.5V</b>

## 5 Absolute Maximum Ratings

Stresses beyond those listed in [Table 2](#) may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in Section 6 Electrical Characteristics on page 4 is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Table 2. Absolute Maximum Ratings

Parameter	Min	Max	Units	Comments
V+, IN1, IN2 to GND	-0.3	+7	V	
COMx, NOx, NCx to GND †	-0.3	V+ + 0.3	V	
COMx, NOx, NCx Continuous Current	-100	+100	mA	
COMx, NOx, NCx Peak Current	-150	+150	mA	Pulsed at 1ms, 10% duty cycle
Continuous Power Dissipation (T <sub>AMB</sub> = +70°C)		330	mW	Derate at 4.7mW/°C above +70°C
Electro-Static Discharge		1000	V	HBM Mil-Std883E 3015.7 methods
Latch Up Immunity		100	mA	Norm: JEDEC 17
Operating Temperature Range	-40	+85	°C	
Junction Temperature		150	°C	
Storage Temperature Range	-65	+150	°C	
Package Body Temperature		+260	°C	The reflow peak soldering temperature (body temperature) specified is in accordance with IPC/JEDEC J-STD-020C "Moisture/Reflow Sensitivity Classification for Non-Hermetic Solid State Surface Mount Devices"

† Signals on pins COM1, COM2, NO1, NO2, NC1, or NC2 that exceed V+ or GND are clamped by internal diodes. Limit forward-diode current to the maximum current rating.

## 6 Electrical Characteristics

$V_+ = +4.5$  to  $5.5V$ ,  $V_{IH} = +2.4V$ ,  $V_{IL} = +0.8V$ ,  $T_{AMB} = T_{MIN}$  to  $T_{MAX}$  (unless otherwise specified). Typ Values @ $T_{AMB} = +25^\circ C$ .

Table 3. +5V Supply Electrical Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit	
<b>Analog Switch</b>							
$V_{COMx}$ , $V_{NOx}$ , $V_{NCx}$	Analog Signal Range		0		$V_+$	V	
$R_{ON}$	ON-Resistance	$V_+ = 4.5V$ , $I_{COMx} = 10mA$ , $V_{NOx}$ or $V_{NCx} = 0$ to $V_+$		$T_{AMB} = +25^\circ C$ $T_{AMB} = T_{MIN}$ to $T_{MAX}$	2.5 4.5	4 $\Omega$	
$\Delta R_{ON}$	ON-Resistance Match Between Channels <sup>1</sup>	$V_+ = 4.5V$ , $I_{COMx} = 10mA$ , $V_{NOx}$ or $V_{NCx} = 0$ to $V_+$		$T_{AMB} = +25^\circ C$ $T_{AMB} = T_{MIN}$ to $T_{MAX}$	0.1 0.4	0.2 $\Omega$	
$R_{FLAT(ON)}$	ON-Resistance Flatness <sup>2</sup>	$V_+ = 4.5V$ , $I_{COMx} = 10mA$ , $V_{NOx}$ or $V_{NCx} = 0$ to $V_+$		$T_{AMB} = +25^\circ C$ $T_{AMB} = T_{MIN}$ to $T_{MAX}$	0.5 1.2	1 $\Omega$	
$I_{NOx(OFF)}$ , $I_{NCx(OFF)}$	$NOx$ or $NCx$ Off-Leakage Current <sup>3</sup>	$V_+ = 5.5V$ , $V_{COMx} = 1$ or $4.5V$ , $V_{NOx}$ or $V_{NCx} = 4.5$ or $1V$		$T_{AMB} = +25^\circ C$ $T_{AMB} = T_{MIN}$ to $T_{MAX}$	-0.1 -0.3	$\pm 0.01$ 0.1 0.3	nA
$I_{COMx(OFF)}$	COMx Off-Leakage Current <sup>3</sup>	$V_+ = 5.5V$ , $V_{COMx} = 1$ or $4.5V$ , $V_{NOx}$ or $V_{NCx} = 4.5$ or $1V$		$T_{AMB} = +25^\circ C$ $T_{AMB} = T_{MIN}$ to $T_{MAX}$	-0.1 -3	$\pm 0.01$ 0.1 3	nA
$I_{COMx(ON)}$	COMx On-Leakage Current <sup>3</sup>	$V_+ = 5.5V$ , $V_{COMx} = 4.5$ or $1V$ , $V_{NOx}$ or $V_{NCx} = 4.5$ or $1V$		$T_{AMB} = +25^\circ C$ $T_{AMB} = T_{MIN}$ to $T_{MAX}$	-0.4 -4	$\pm 0.1$ 0.4 4	nA
<b>Logic Input: INx</b>							
$V_{IH}$	Input Logic High		2.4			V	
$V_{IL}$	Input Logic Low				0.8	V	
$I_{IH}$ , $I_{IL}$	Input Leakage Current	$V_{INx} = 0$ or $+5.5V$	-100		5 100	nA	
<b>Switch Dynamic Characteristics</b>							
$t_{ON}$	Turn On Time <sup>3</sup>	$V_{NOx}$ or $V_{NCx} = 3V$ , $R_{LOAD} = 300\Omega$ , $C_{LOAD} = 35pF$ , Figure 12		$T_{AMB} = +25^\circ C$ $T_{AMB} = T_{MIN}$ to $T_{MAX}$	14 18	17 ns	
$t_{OFF}$	Turn Off Time <sup>3</sup>	$V_{NOx}$ or $V_{NCx} = 3V$ , $R_{LOAD} = 300\Omega$ , $C_{LOAD} = 35pF$ , Figure 12		$T_{AMB} = +25^\circ C$ $T_{AMB} = T_{MIN}$ to $T_{MAX}$	4 8	6 ns	
$t_{BBM}$	Break-Before-Make <sup>3</sup>	$V_{NOx}$ or $V_{NCx} = 3V$ , $R_{LOAD} = 300\Omega$ , $C_{LOAD} = 35pF$ , Figure 13		$T_{AMB} = +25^\circ C$ $T_{AMB} = T_{MIN}$ to $T_{MAX}$	10 1	ns	
$Q$	Charge Injection	$V_{GEN} = 2V$ , $R_{GEN} = 0$ , $C_{LOAD} = 1.0nF$ , Figure 14			7	pC	
$C_{NOx(OFF)}$ , $C_{NCx(OFF)}$	$NOx$ , $NCx$ Off-Capacitance	$V_{NOx}$ or $V_{NCx} = GND$ , $f = 1MHz$ , Figure 15			20	pF	
$C_{COMx(ON)}$	COMx On-Capacitance	$V_{COMx} = GND$ , $f = 1MHz$ , Figure 15			56	pF	
$V_{ISO}$	Off-Isolation <sup>4</sup>	$f = 10MHz$ , $R_{LOAD} = 50\Omega$ , $C_{LOAD} = 5pF$ , Figure 16 $f = 1MHz$ , $R_{LOAD} = 50\Omega$ , $C_{LOAD} = 5pF$ , Figure 16			-52 -85	dB	
$V_{CT}$	Crosstalk <sup>5</sup>	$f = 10MHz$ , $R_{LOAD} = 50\Omega$ , $C_{LOAD} = 5pF$ , Figure 16 $f = 1MHz$ , $R_{LOAD} = 50\Omega$ , $C_{LOAD} = 5pF$ , Figure 16			-52 -90	dB	
$THD$	Total Harmonic Distortion	$f = 20Hz$ to $20kHz$ , $V_{NOx} = 5Vp-p$ , $R_{LOAD} = 600\Omega$			0.1	%	
<b>Power Supply</b>							
$I_+$	Positive Supply Current	$V_+ = 5.5V$ , $V_{INx} = 0$ or $V_+$			0.01 1.0	$\mu A$	

$V_+ = +2.7$  to  $3.6V$ ,  $V_{IH} = +2.0V$ ,  $V_{IL} = +0.4V$ ,  $T_{AMB} = T_{MIN}$  to  $T_{MAX}$  (unless otherwise specified). Typ values @  $T_{AMB} = +25^\circ C$ .

Table 4. +3V Supply Electrical Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Analog Switch</b>						
$V_{COMx}$ , $V_{NOx}$ , $V_{NCx}$	Analog Signal Range		0		$V_+$	V
$R_{ON}$	ON-Resistance	$V_+ = 2.7V$ , $I_{COMx} = 10mA$ , $V_{NOx}$ or $V_{NCx} = 0$ to $V_+$		5	5.5	$\Omega$
					8	
$\Delta R_{ON}$	ON-Resistance Match Between Channels <sup>1</sup>	$V_+ = 2.7V$ , $I_{COMx} = 10mA$ , $V_{NOx}$ or $V_{NCx} = 0$ to $V_+$		0.1	0.2	$\Omega$
					0.4	
$R_{FLAT(ON)}$	ON-Resistance Flatness <sup>2</sup>	$V_+ = 2.7V$ , $I_{COMx} = 10mA$ , $V_{NOx}$ or $V_{NCx} = 0$ to $V_+$		1.5	2	$\Omega$
					2.5	
$I_{NOx(OFF)}$ , $I_{NCx(OFF)}$	$NOx$ or $NCx$ Off-Leakage Current <sup>3</sup>	$V_+ = 3.3V$ , $V_{COMx} = 1$ or $3V$ , $V_{NOx}$ or $V_{NCx} = 3$ or $1V$		$\pm 0.01$	0.1	nA
					0.3	
$I_{COMx(OFF)}$	$COMx$ Off-Leakage Current <sup>3</sup>	$V_+ = 3.3V$ , $V_{COMx} = 1$ or $3V$ , $V_{NOx}$ or $V_{NCx} = 3$ or $1V$		$\pm 0.01$	0.1	nA
					3	
$I_{COMx(ON)}$	$COMx$ On-Leakage Current <sup>3</sup>	$V_+ = 3.3V$ , $V_{COMx} = 1$ or $3V$ , $V_{NOx}$ or $V_{NCx} = 1$ or $3V$		$\pm 0.1$	0.4	nA
					4	
<b>Logic Input: (<math>I_{Nx}</math>)</b>						
$V_{IH}$	Input Logic High		2.0			V
$V_{IL}$	Input Logic Low				0.4	V
$I_{IH}, I_{IL}$	Input Leakage Current	$V_{INx} = 0$ or $+5.5V$	-100	5	100	nA
<b>Switch Dynamic Characteristics</b>						
$t_{ON}$	Turn On Time <sup>3</sup>	$V_{NOx}$ or $V_{NCx} = 2V$ , $R_{LOAD} = 300\Omega$ , $C_{LOAD} = 35pF$ , Figure 12			17	ns
					23	
$t_{OFF}$	Turn Off Time <sup>3</sup>	$V_{NOx}$ or $V_{NCx} = 2V$ , $R_{LOAD} = 300\Omega$ , $C_{LOAD} = 35pF$ , Figure 12			6	ns
					8	
$t_{BBM}$	Break-Before-Make <sup>3</sup>	$V_{NOx}$ or $V_{NCx} = 2V$ , $R_{LOAD} = 300\Omega$ , $C_{LOAD} = 35pF$ , Figure 13			11	ns
					1	
$Q$	Charge Injection	$V_{GEN} = 1.5V$ , $R_{GEN} = 0$ , $C_{LOAD} = 1.0nF$ , Figure 14			0	pC
$C_{NOx(OFF)}$ , $C_{NCx(OFF)}$	$NOx$ , $NCx$ Off-Capacitance	$V_{NOx}$ or $V_{NCx} = GND$ , $f = 1MHz$ , Figure 15			20	pF
$C_{COMx(ON)}$	$COMx$ On-Capacitance	$V_{COMx} = GND$ , $f = 1MHz$ , Figure 15			56	pF
$V_{ISO}$	Off-Isolation <sup>4</sup>	$f = 10MHz$ , $R_{LOAD} = 50\Omega$ , $C_{LOAD} = 5pF$ , Figure 16			-52	dB
		$f = 1MHz$ , $R_{LOAD} = 50\Omega$ , $C_{LOAD} = 5pF$ , Figure 16			-85	
$V_{CT}$	Crosstalk <sup>5</sup>	$f = 10MHz$ , $R_{LOAD} = 50\Omega$ , $C_{LOAD} = 5pF$ , Figure 16			-52	dB
		$f = 1MHz$ , $R_{LOAD} = 50\Omega$ , $C_{LOAD} = 5pF$ , Figure 16			-90	
<b>Power Supply</b>						
$I_+$	Positive Supply Current	$V_+ = 3.6V$ , $V_{IN} = 0$ or $+3.6V$		0.01	1.0	$\mu A$

1.  $\Delta R_{ON} = R_{ON(MAX)} - R_{ON(MIN)}$ .

2. Flatness is defined as the difference between the maximum and the minimum value of ON-resistance as measured over the specified analog signal ranges.

3. Guaranteed by design.

4. Off-Isolation =  $20\log_{10}(V_{COMx}/V_{NOx})$ ,  $V_{COMx}$  = output,  $V_{NOx}$  = input to off switch.

5. Between any two switches.

## 7 Typical Operating Characteristics

Figure 3. Frequency Response

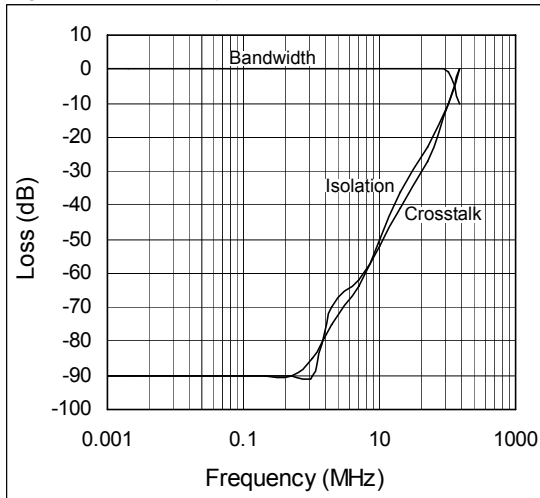


Figure 4. THD vs. Frequency

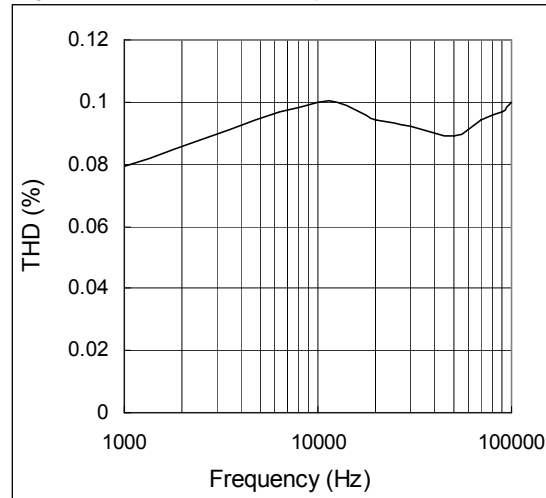


Figure 5.  $R_{ON}$  vs.  $V_{COM}$  and Temperature ( $V_{DD} = 5V$ )

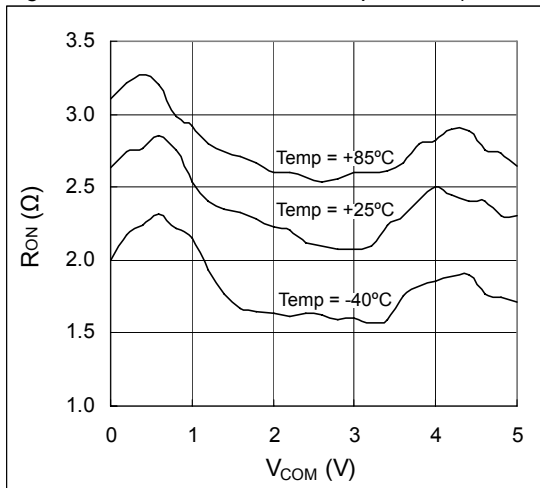


Figure 6.  $R_{ON}$  vs.  $V_{COM}$  and Temperature ( $V_{DD} = 3V$ )

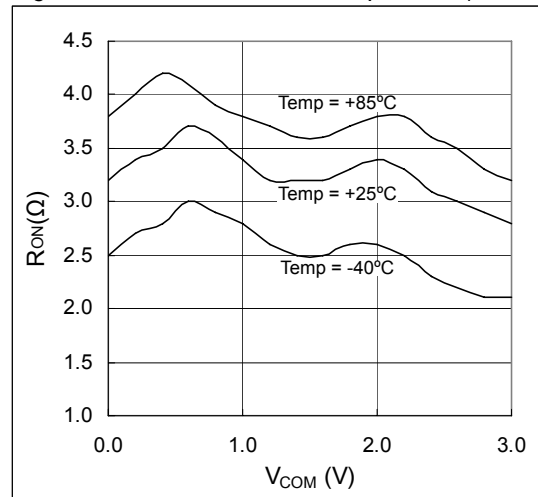


Figure 7.  $R_{ON}$  vs.  $V_{COM}$

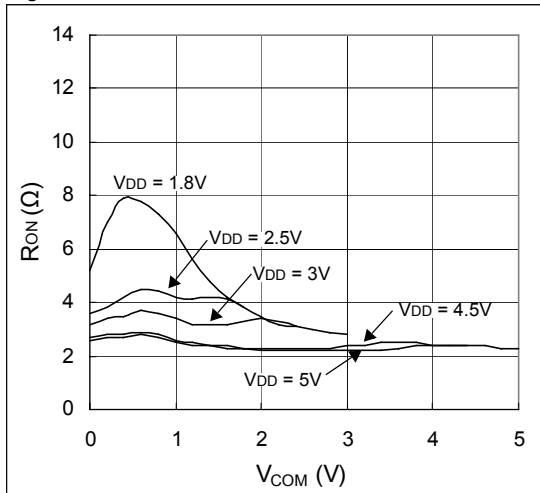


Figure 8.  $t_{ON}/t_{OFF}$  vs. Temperature ( $V_+ = 5V$ )

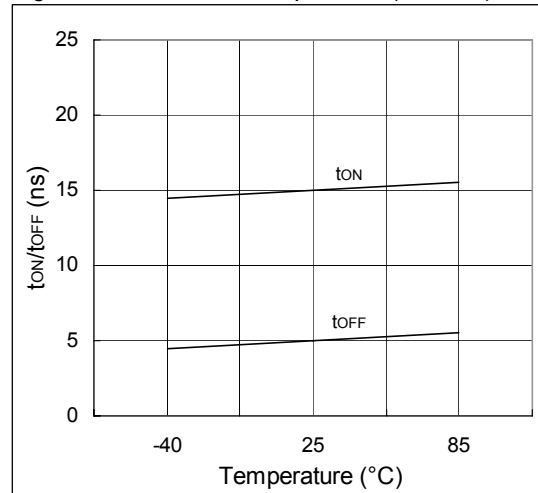


Figure 9.  $t_{ON}/t_{OFF}$  vs. Supply Voltage

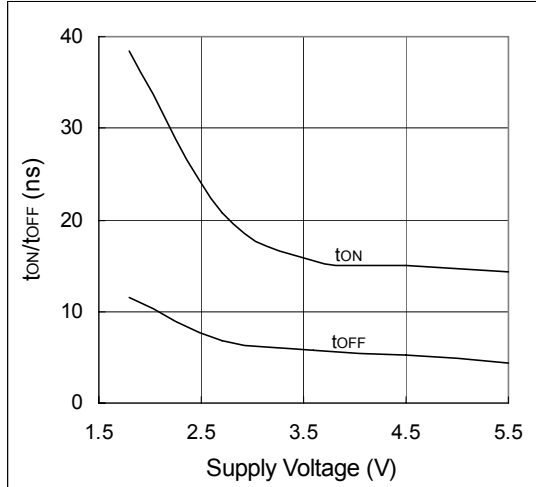
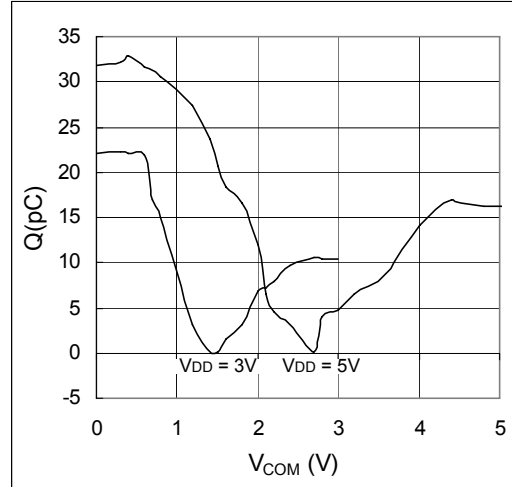


Figure 10. Charge Injection



## 8 Detailed Description

The AS1744/AS1745 are low  $R_{ON}$ , low-voltage, dual analog SPDT switches that operate from a single +1.8 to +5.5V supply.

CMOS process technology allows switching of analog signals that are within the supply voltage range (GND to  $V+$ ).

### ON-Resistance

When powered from a +5V supply, the low  $R_{ON}$  ( $4\Omega$  max) allows high continuous currents to be switched in a wide range of applications. All devices have low  $R_{ON}$  flatness ( $1\Omega$ , max) so they can meet or exceed the low-distortion audio requirements of modern portable audio devices.

### Bi-Directional Switching

Pins  $NO_x$ ,  $NC_x$ , and  $COM_x$  are bi-directional, thus they can be used as inputs or outputs.

### Analog Signal Levels

Analog signals ranging over the entire supply voltage ( $V+$  to GND) can be passed with very little change in ON-resistance (see [Typical Operating Characteristics on page 6](#)).

### Logic Inputs

The AS1744/AS1745 logic inputs ( $IN_x$ ) can be driven up to +5.5V regardless of the supply voltage value. For example, with a +3.3V supply,  $IN+$  may be driven low to GND and high to +5.5V. This allows the devices to interface with +5V systems using a supply of less than 5V.



## 9 Application Information

### Power-Supply Sequencing

Proper power-supply sequencing is critical for proper operation. The recommended sequence is as follows:

1. V+
2. NO<sub>x</sub>, NC<sub>x</sub>, COM<sub>x</sub>

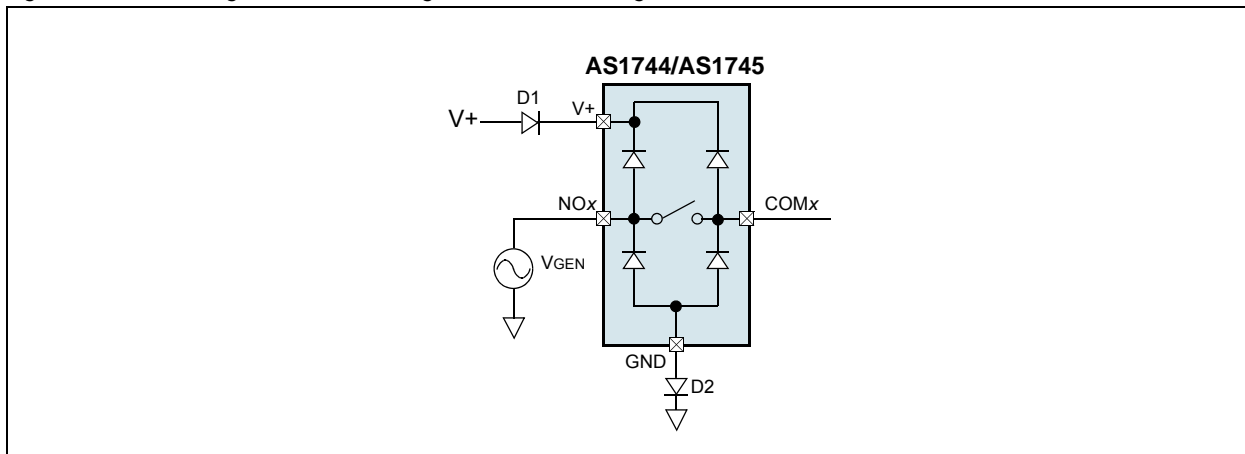
Always apply V+ before applying analog signals, especially if the analog signal is not current-limited. If the above sequence is not possible, and if the analog inputs are not current-limited to less than 30mA, add a small-signal diode as shown in Figure 11 (D1). If the analog signal can dip below GND, add diode D2. Adding these diodes will reduce the analog range to a diode-drop (about 0.7V) below V+ (for D1), and a diode-drop above ground (for D2).

**Note:** Operation beyond the absolute maximum ratings (see page 3) may permanently damage the devices.

### Overvoltage Protection

ON-resistance increases slightly at lower supply voltages.

Figure 11. Overvoltage Protection Using 2 External Blocking Diodes



Adding diode D2 to the circuit shown in Figure 11 causes the logic threshold to be shifted relative to GND. Diodes D1 and D2 also protect against overvoltage conditions.

For example, in the circuit shown in Figure 11, if the supply voltage goes below the absolute maximum rating, and if a fault voltage up to the absolute maximum rating is applied to an analog signal pin, no damage will result.

**Note:** The supply voltage (V+) must not exceed the absolute maximum rating of +7V.

### Power Supply Bypass

Power supply connections to the devices must maintain a low impedance to ground. This can be done using a bypass capacitor, which will also improve noise margin and prevent switching noise propagation from the V+ supply to other components.

### Layout Considerations

High-speed switches require proper layout and design procedures for optimum performance.

- Reduce stray inductance and capacitance by keeping traces short and wide.
- Ensure that bypass capacitors are as close to the device as possible.
- Use large ground planes where possible.

## Timing Diagrams and Test Setups

Figure 12. Switching Time

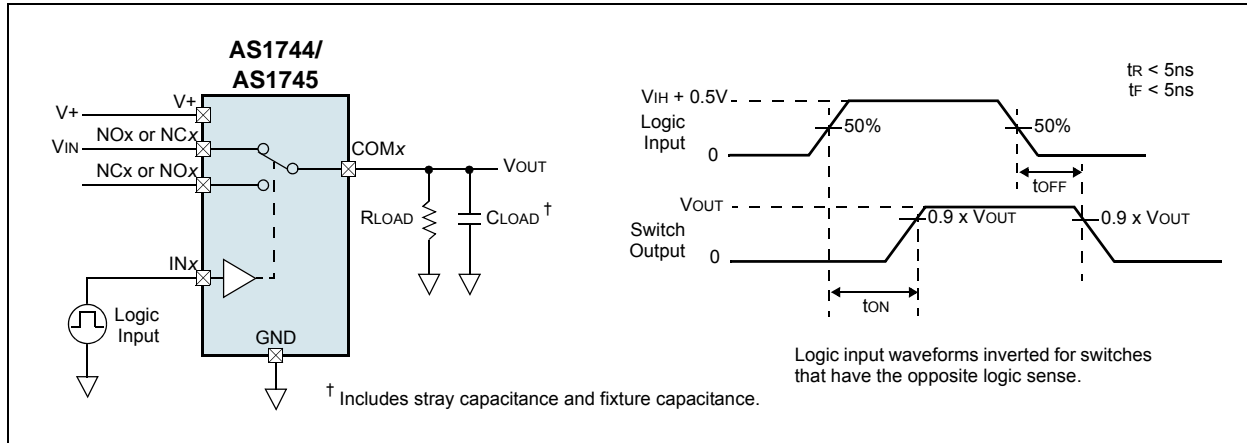


Figure 13. Break-Before-Make Interval

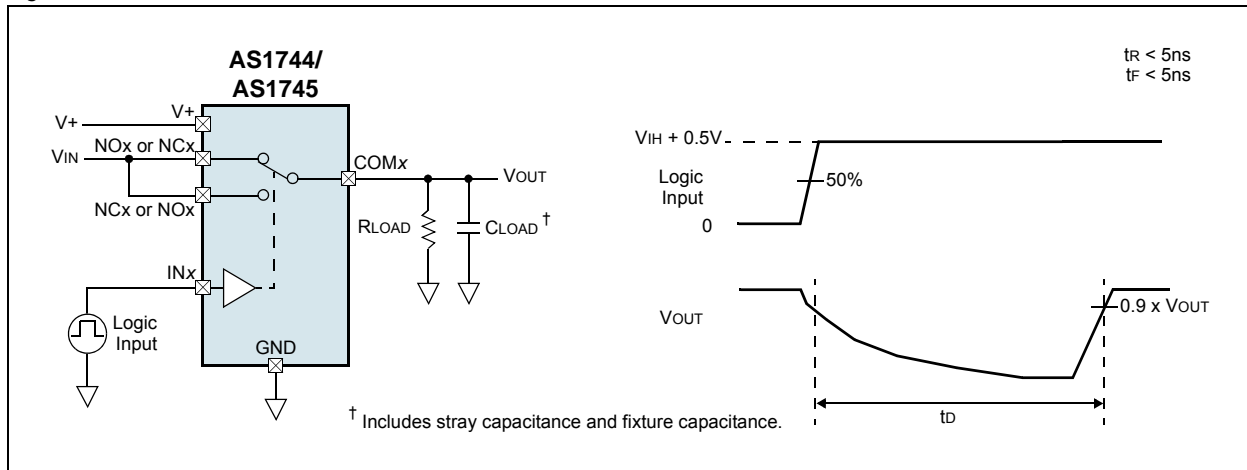


Figure 14. Charge Injection

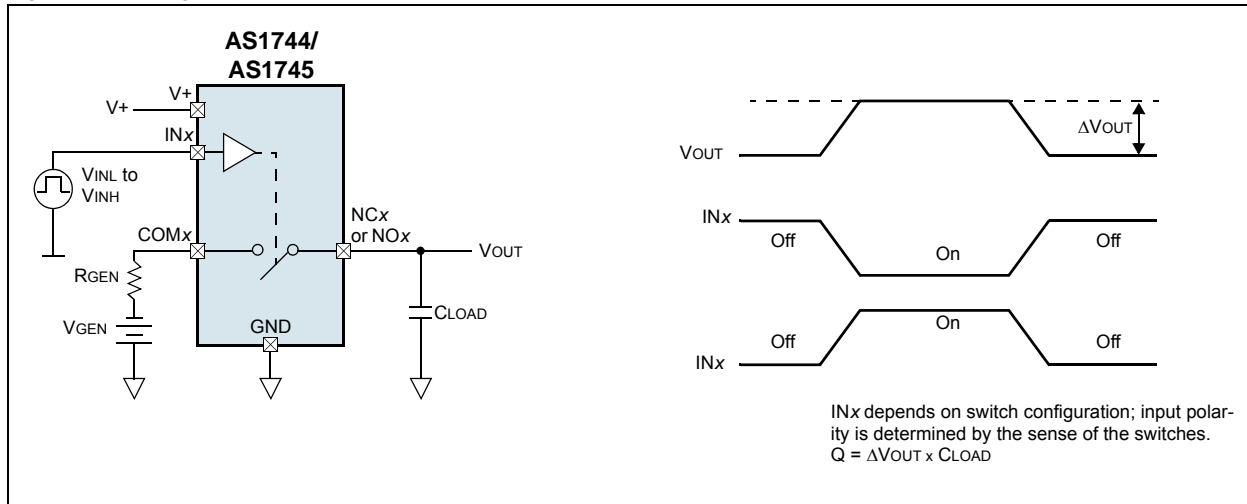


Figure 15. NOx, NCx, and COMx Capacitance

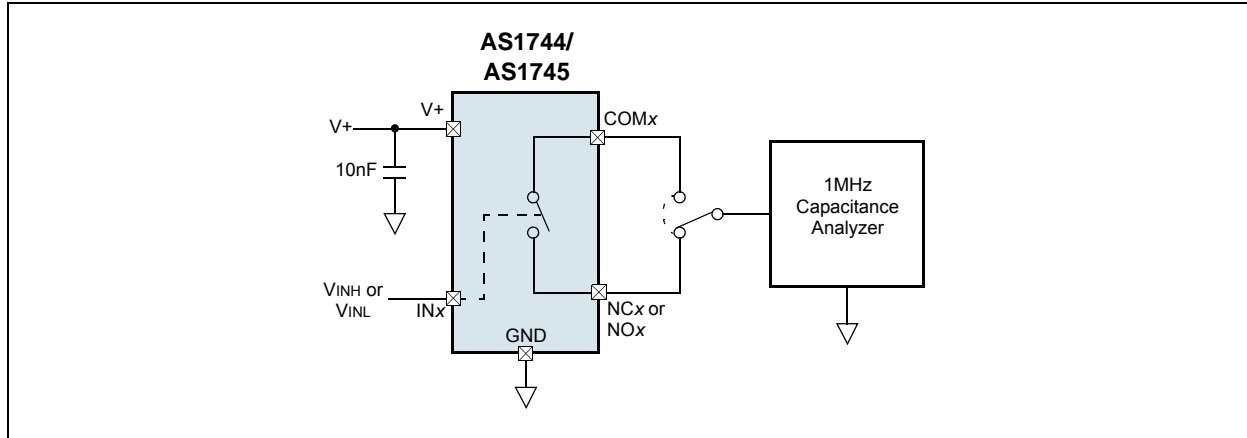
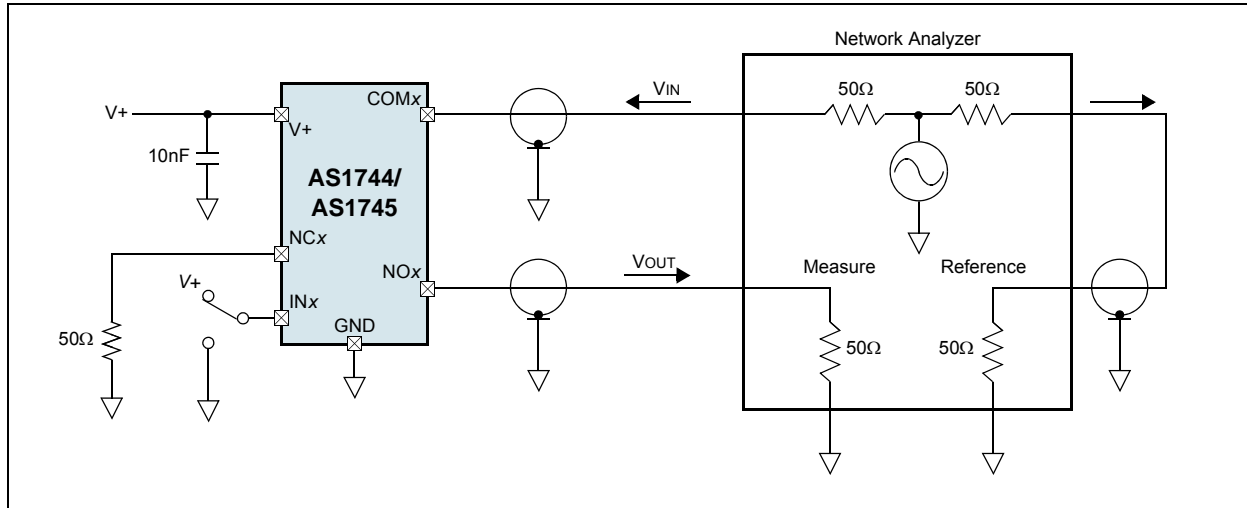


Figure 16. Off-Isolation, On-Loss, and Crosstalk



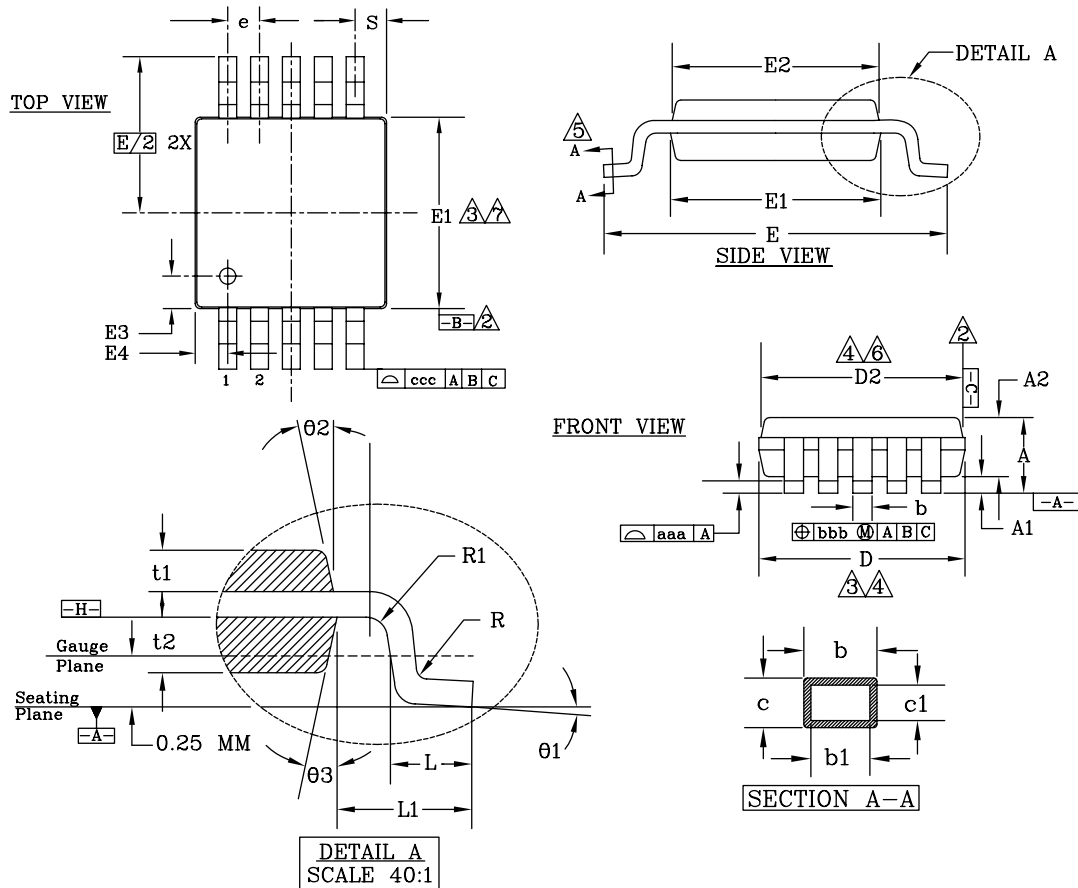
**Notes:**

1. Measurements are standardized against short-circuit at all terminals.
2. Off-isolation is measured between COMx and the off NCx/NOx terminal of each switch. Off-isolation =  $20\log(V_{OUT}/V_{IN})$ .
3. Crosstalk is measured from one channel to all other channels.
4. Signal direction through the switch is reversed; worst values are recorded.

## Package Drawings and Markings

The devices are available in a 10-pin MSOP package and a 10-pin TDFN package.

Figure 17. 10-pin MSOP Package

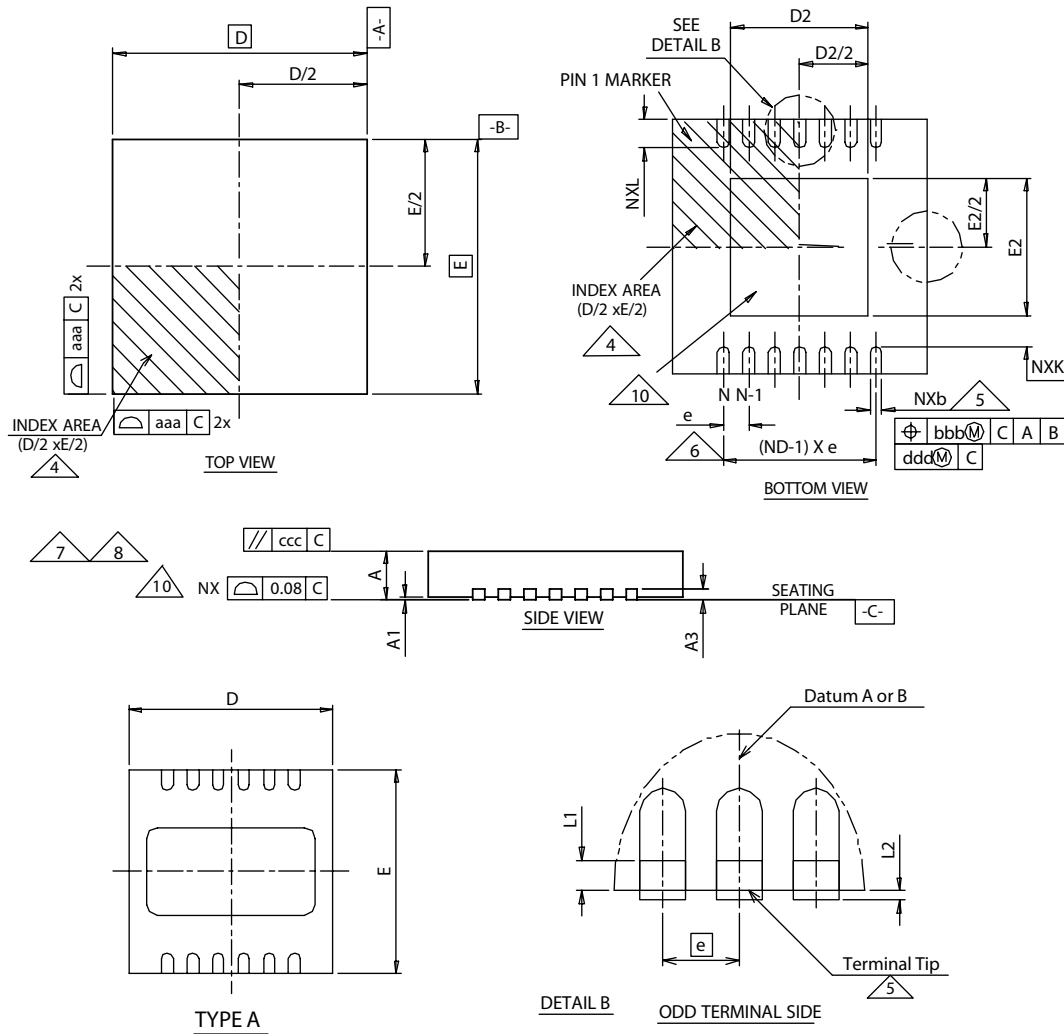


Symbol	Typ	±Tol	Symbol	Typ	±Tol
A	1.10	Max	b	0.23	+0.07/-0.08
A1	0.10	±0.05	b1	0.20	±0.05
A2	0.86	±0.08	c	0.18	±0.08
D	3.00	±0.10	c1	0.15	+0.03/-0.02
D2	2.95	±0.10	θ1	3.0°	±3.0°
E	4.90	±0.15	θ2	12.0°	±3.0°
E1	3.00	±0.10	θ3	12.0°	±3.0°
E2	2.95	±0.10	L	0.55	±0.15
E3	0.51	±0.13	L1	0.95BSC	-
E4	0.51	±0.13	aaa	0.10	-
R	0.15	+0.15/-0.08	bbb	0.08	-
R1	0.15	+0.15/-0.08	ccc	0.25	-
t1	0.31	±0.08	e	0.50 BSC	-
t2	0.41	±0.08	S	0.50 BSC	-

**Notes:**

1. All dimensions are in millimeters, angles in degrees, unless otherwise specified.
2. Datums B and C to be determined at datum plane H.
3. Dimensions D and E1 are to be determined at datum plane H.
4. Dimensions D2 and E2 are for top package; dimensions D and E1 are for bottom package.
5. Cross section A-A to be determined at 0.13 to 0.25mm from lead tip.
6. Dimensions D and D2 do not include mold flash, protrusion, or gate burrs.
7. Dimensions E1 and E2 do not include interlead flash or protrusion.

Figure 18. 10-pin TDFN Package (3.0x3.0mm)



Symbol	Min	Typ	Max	Notes
A	0.70	0.75	0.80	1, 2
A1	0.00	0.02	0.05	1, 2
A3		0.20 REF		1, 2
L1			0.15	1, 2
L2			0.13	1, 2
$\theta$	0°		14°	1, 2
K	0.20			1, 2
K2	0.17			1, 2
b	0.18	0.25	0.30	1, 2, 5
e		0.5		
aaa		0.15		1, 2
bbb		0.10		1, 2
ccc		0.10		1, 2
ddd		0.05		1, 2
eee		0.08		1, 2
ggg		0.10		1, 2

Variations				
Symbol	Min	Typ	Max	Notes
D BSC		3.00		1, 2
E BSC		3.00		1, 2
D2	2.20		2.70	1, 2
E2	1.40		1.75	1, 2
L	0.30	0.40	0.50	1, 2
N		10		1, 2
ND		5		1, 2, 5

**Notes:**

1. Dimensioning and tolerancing are compliant with *ASME Y14.5M-1994*.
2. Dimensions are in millimeters, angles in degrees (°).
3. N is the total number of terminals.
4. The terminal 1 identifier and terminal numbering convention shall conform to *JESD 95-1 SPP-012*. Details of terminal 1 identifier are optional, but must be located within the zone indicated. The terminal 1 identifier may be either a mold, embedded metal or mark feature.
5. Dimension b applies to metallized terminal and is measured between 0.15 and 0.30mm from terminal tip.
6. ND refers to the maximum number of terminals on D side.
7. Variation shown in [Figure 18](#) is for illustration purposes only.
8. For variation identifier dimension details, refer to the Dimensions table.
9. For a complete set of dimensions for each variation, refer to the Variations table.
10. Unilateral coplanarity zone applies to the exposed heat sink slug and the terminals.
11. For a rectangular package, the terminal side of the package is determined by:
  - Type 1: Terminals are on the short side of the package.
  - Type 2: Terminals are on the long side of the package.
12. Variations specified as NJR (non JEDEC registered), with an additional dash number (e.g., -1, -2) are packages currently not registered with JEDEC.
13. When more than one variations exist for the same profile height, body size (DxE), and pitch, then those variations will be denoted by an additional dash number (i.e., -1,-2) for identification. The new variations shall be created based on any or all of the following factors: terminal count, terminal length, and exposed pad sizes.

## 10 Ordering Information

The devices are available as the standard products shown in [Table 5](#).

Table 5. Ordering Information

Type	Description	Delivery Form	Package
AS1744G	Dual SPDT Switch	Tube	10-pin MSOP
AS1744G-T	Dual SPDT Switch	Tape and Reel	10-pin MSOP
AS1744V-T <sup>†</sup>	Dual SPDT Switch	Tape and Reel	10-pin TDFN
AS1745G	Dual SPDT Switch	Tube	10-pin MSOP
AS1745G-T	Dual SPDT Switch	Tape and Reel	10-pin MSOP
AS1745V-T <sup>†</sup>	Dual SPDT Switch	Tape and Reel	10-pin TDFN

<sup>†</sup> Available upon request. Contact austriamicrosystems, AG for details.



## Copyrights

Copyright © 1997-2007, austriamicrosystems AG, Schloss Premstaetten, 8141 Unterpremstaetten, Austria-Europe. Trademarks Registered ®. All rights reserved. The material herein may not be reproduced, adapted, merged, translated, stored, or used without the prior written consent of the copyright owner.

All products and companies mentioned are trademarks or registered trademarks of their respective companies.

## Disclaimer

Devices sold by austriamicrosystems AG are covered by the warranty and patent indemnification provisions appearing in its Term of Sale. austriamicrosystems AG makes no warranty, express, statutory, implied, or by description regarding the information set forth herein or regarding the freedom of the described devices from patent infringement. austriamicrosystems AG reserves the right to change specifications and prices at any time and without notice. Therefore, prior to designing this product into a system, it is necessary to check with austriamicrosystems AG for current information. This product is intended for use in normal commercial applications. Applications requiring extended temperature range, unusual environmental requirements, or high reliability applications, such as military, medical life-support or life-sustaining equipment are specifically not recommended without additional processing by austriamicrosystems AG for each application. For shipments of less than 100 parts the manufacturing flow might show deviations from the standard production flow, such as test flow or test location.

The information furnished here by austriamicrosystems AG is believed to be correct and accurate. However, austriamicrosystems AG shall not be liable to recipient or any third party for any damages, including but not limited to personal injury, property damage, loss of profits, loss of use, interruption of business or indirect, special, incidental or consequential damages, of any kind, in connection with or arising out of the furnishing, performance or use of the technical data herein. No obligation or liability to recipient or any third party shall arise or flow out of austriamicrosystems AG rendering of technical or other services.



## Contact Information

### Headquarters

austriamicrosystems AG  
A-8141 Schloss Premstaetten, Austria

Tel: +43 (0) 3136 500 0  
Fax: +43 (0) 3136 525 01

For Sales Offices, Distributors and Representatives, please visit:

<http://www.austriamicrosystems.com/contact>